- **Driver Version of ′AS00**
- **High Capacitive-Drive Capability**
- **Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

## description

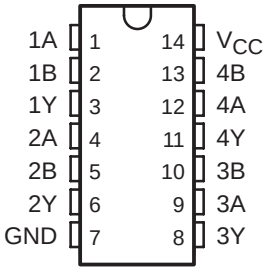
These devices contain four independent 2-input positive-NAND buffers/drivers. They perform the Boolean functions $Y = \overline{A \bullet B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

The SN54AS1000A is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74AS1000A is characterized for operation from 0°C to 70°C.

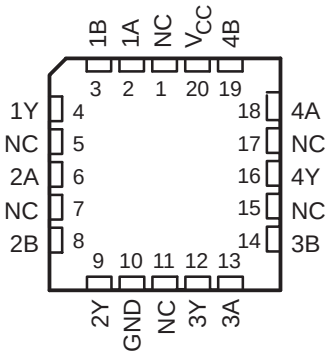
**FUNCTION TABLE**
**(each gate)**

| INPUTS | | OUTPUT |
|---|---|---|
| A | B | Y |
| H | H | L |
| L | X | H |
| X | L | H |

**SN54AS1000A . . . J PACKAGE**
**SN74AS1000A . . . D OR N PACKAGE**
**(TOP VIEW)**

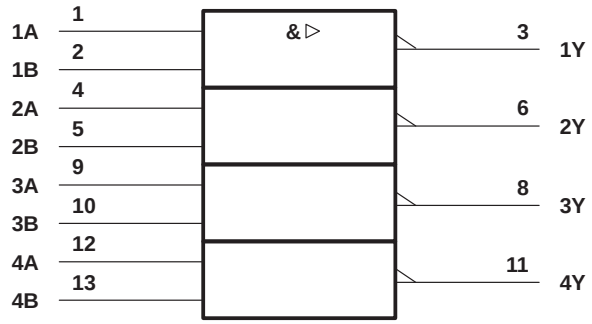



**SN54AS1000A . . . FK PACKAGE**
**(TOP VIEW)**




NC − No internal connection

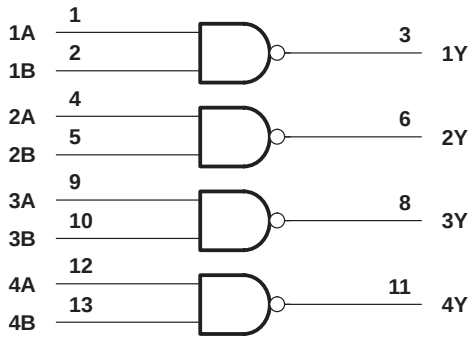
## logic symbol†




† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

## logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$ . . . . . 7 V
Input voltage, $V_I$ . . . . . 7 V
Operating free-air temperature range, $T_A$: SN54AS1000A . . . . . −55°C to 125°C
SN74AS1000A . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions‡

| | | SN54AS1000A | | | SN74AS1000A | | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| $V_{IH}$ | High-level input voltage | 2 | | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| $I_{OH}$ | High-level output current | | | −40 | | | −48 | mA |
| $I_{OL}$ | Low-level output current | | | 40 | | | 48 | mA |
| $T_A$ | Operating free-air temperature | −55 | | 125 | 0 | | 70 | °C |

‡ These high sink- or source-current devices are not recommended for use above 40 MHz.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | SN54AS1000A | | | SN74AS1000A | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | TYP§ | MAX | MIN | TYP§ | MAX | |
| $V_{IK}$ | $V_{CC}$ = 4.5 V, | $I_I$ = −18 mA | | | −1.2 | | | −1.2 | V |
| $V_{OH}$ | $V_{CC}$ = 4.5 V to 5.5 V, | $I_{OH}$ = −2 mA | $V_{CC}$ −2 | | | $V_{CC}$ −2 | | | V |
| | $V_{CC}$ = 4.5 V | $I_{OH}$ = −3 mA | 2.4 | 3.2 | | 2.4 | 3.2 | | |
| | | $I_{OH}$ = −40 mA | 2 | | | | | | |
| | | $I_{OH}$ = −48 mA | | | | 2 | | | |
| $V_{OL}$ | $V_{CC}$ = 4.5 V | $I_{OL}$ = 40 mA | | 0.25 | 0.5 | | | | V |
| | | $I_{OL}$ = 48 mA | | | | | 0.35 | 0.5 | |
| $I_I$ | $V_{CC}$ = 5.5 V, | $V_I$ = 7 V | | | 0.1 | | | 0.1 | mA |
| $I_{IH}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 2.7 V | | | 20 | | | 20 | µA |
| $I_{IL}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 0.4 V | | | −0.5 | | | −0.5 | mA |
| $I_O$¶ | $V_{CC}$ = 5.5 V, | $V_O$ = 2.25 V | −30 | | −200 | −50 | | −200 | mA |
| $I_{CCH}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 0 | | 2.2 | 3.5 | | 2.2 | 3.5 | mA |
| $I_{CCL}$ | $V_{CC}$ = 5.5 V, | $V_I$ = 4.5 V | | 12 | 19 | | 12 | 19 | mA |

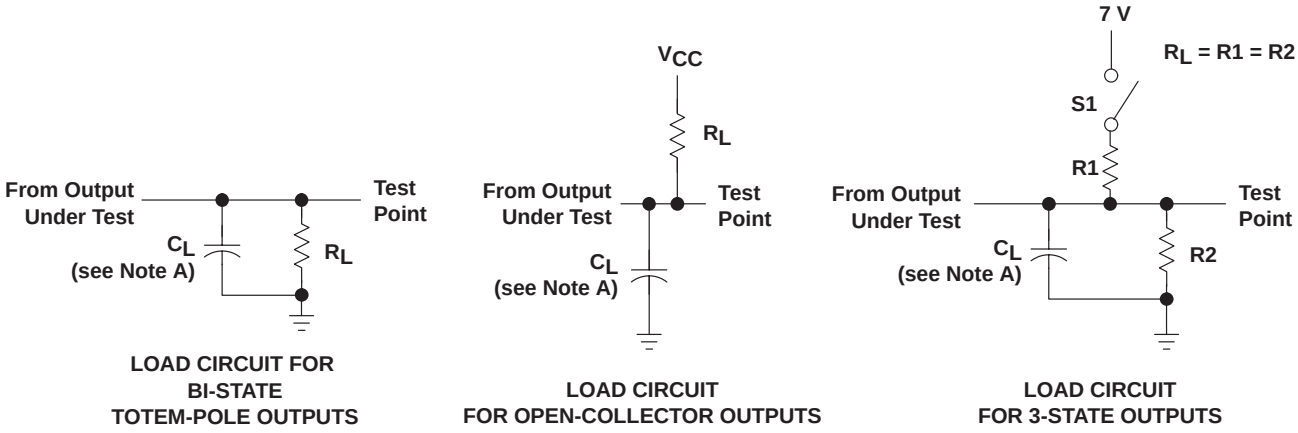
§ All typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.
¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, $I_{OS}$.

## switching characteristics (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC}$ = 4.5 V to 5.5 V, $C_L$ = 50 pF, $R_L$ = 500 Ω, $T_A$ = MIN to MAX† | | | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | SN54AS1000A | | SN74AS1000A | | |
| | | | MIN | MAX | MIN | MAX | |
| $t_{PLH}$ | A or B | Y | 1 | 5 | 1 | 4 | ns |
| $t_{PHL}$ | | | 1 | 5 | 1 | 4 | |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

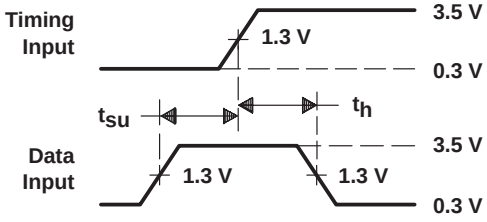
## PARAMETER MEASUREMENT INFORMATION
## SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



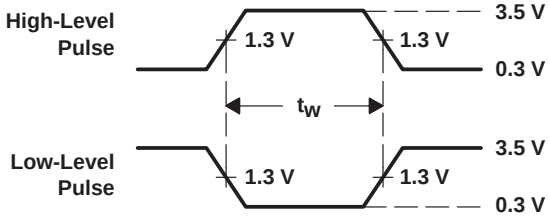

LOAD CIRCUIT FOR BI-STATE TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR OPEN-COLLECTOR OUTPUTS

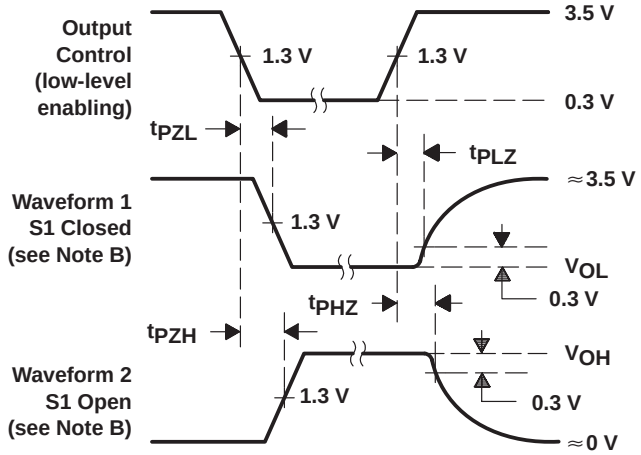
LOAD CIRCUIT FOR 3-STATE OUTPUTS



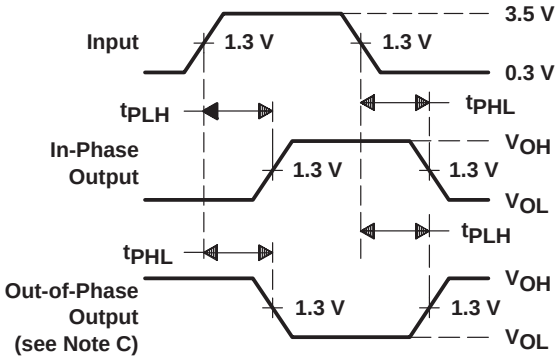

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS PULSE DURATIONS




VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS




VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f$ = 2 ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuits and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package \| Pins | Package qty \| Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|---|---|---|---|---|---|---|---|---|---|
| 5962-9162701M2A | Active | Production | LCCC (FK) \| 20 | 55 \| TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-9162701M2A SNJ54AS1000AFK |
| 5962-9162701MCA | Active | Production | CDIP (J) \| 14 | 25 \| TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-9162701MCA SNJ54AS1000AJ |
| SN74AS1000AD | Obsolete | Production | SOIC (D) \| 14 | - | - | Call TI | Call TI | 0 to 70 | AS1000A |
| SN74AS1000ADR | Active | Production | SOIC (D) \| 14 | 2500 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | AS1000A |
| SN74AS1000AN | Active | Production | PDIP (N) \| 14 | 25 \| TUBE | Yes | NIPDAU | N/A for Pkg Type | 0 to 70 | SN74AS1000AN |
| SN74AS1000ANSR | Active | Production | SOP (NS) \| 14 | 2000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74AS1000A |
| SNJ54AS1000AFK | Active | Production | LCCC (FK) \| 20 | 55 \| TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-9162701M2A SNJ54AS1000AFK |
| SNJ54AS1000AJ | Active | Production | CDIP (J) \| 14 | 25 \| TUBE | No | SNPB | N/A for Pkg Type | -55 to 125 | 5962-9162701MCA SNJ54AS1000AJ |

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.



**OTHER QUALIFIED VERSIONS OF SN54AS1000A, SN74AS1000A :**

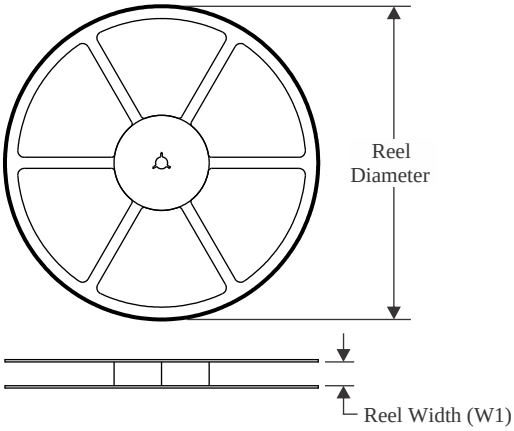
- Catalog : SN74AS1000A
- Military : SN54AS1000A

NOTE: Qualified Version Definitions:

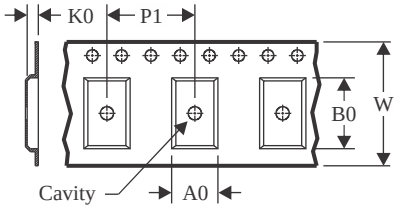
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

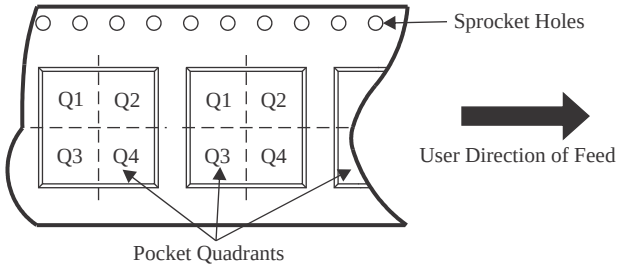



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

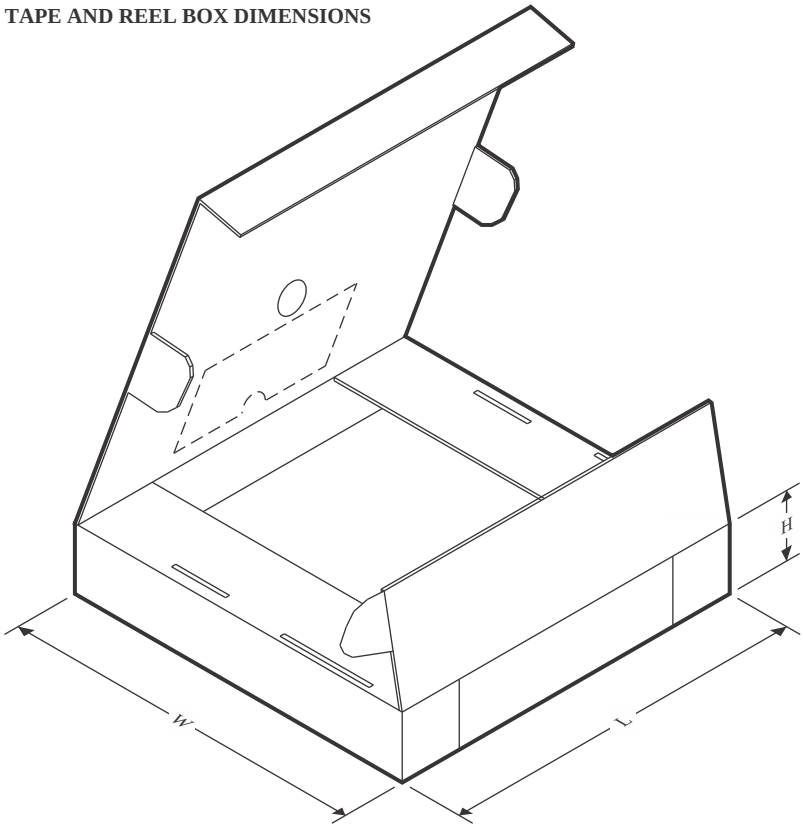
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74AS1000ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74AS1000ANSR | SOP | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

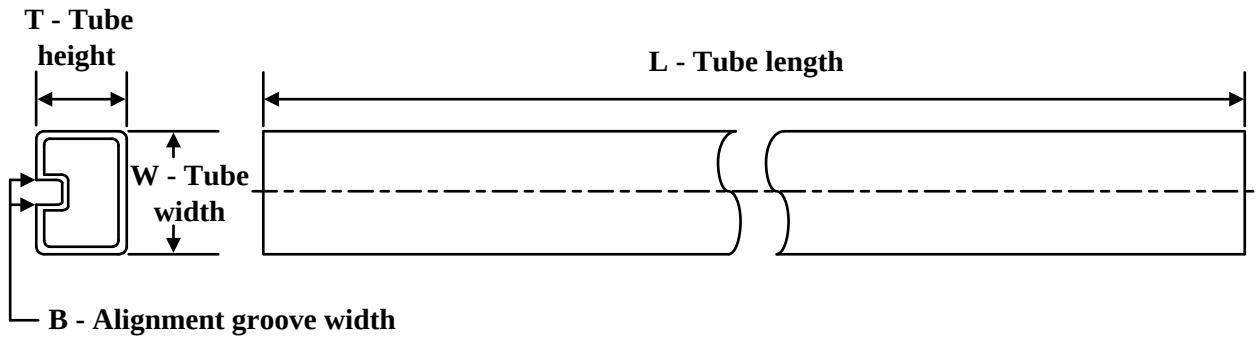
TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

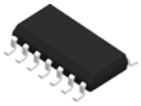
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74AS1000ADR | SOIC | D | 14 | 2500 | 356.0 | 356.0 | 35.0 |
| SN74AS1000ANSR | SOP | NS | 14 | 2000 | 356.0 | 356.0 | 35.0 |

## TUBE




*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---|---|---|---|---|---|---|---|---|
| 5962-9162701M2A | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |
| SN74AS1000AN | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74AS1000AN | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SNJ54AS1000AFK | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |

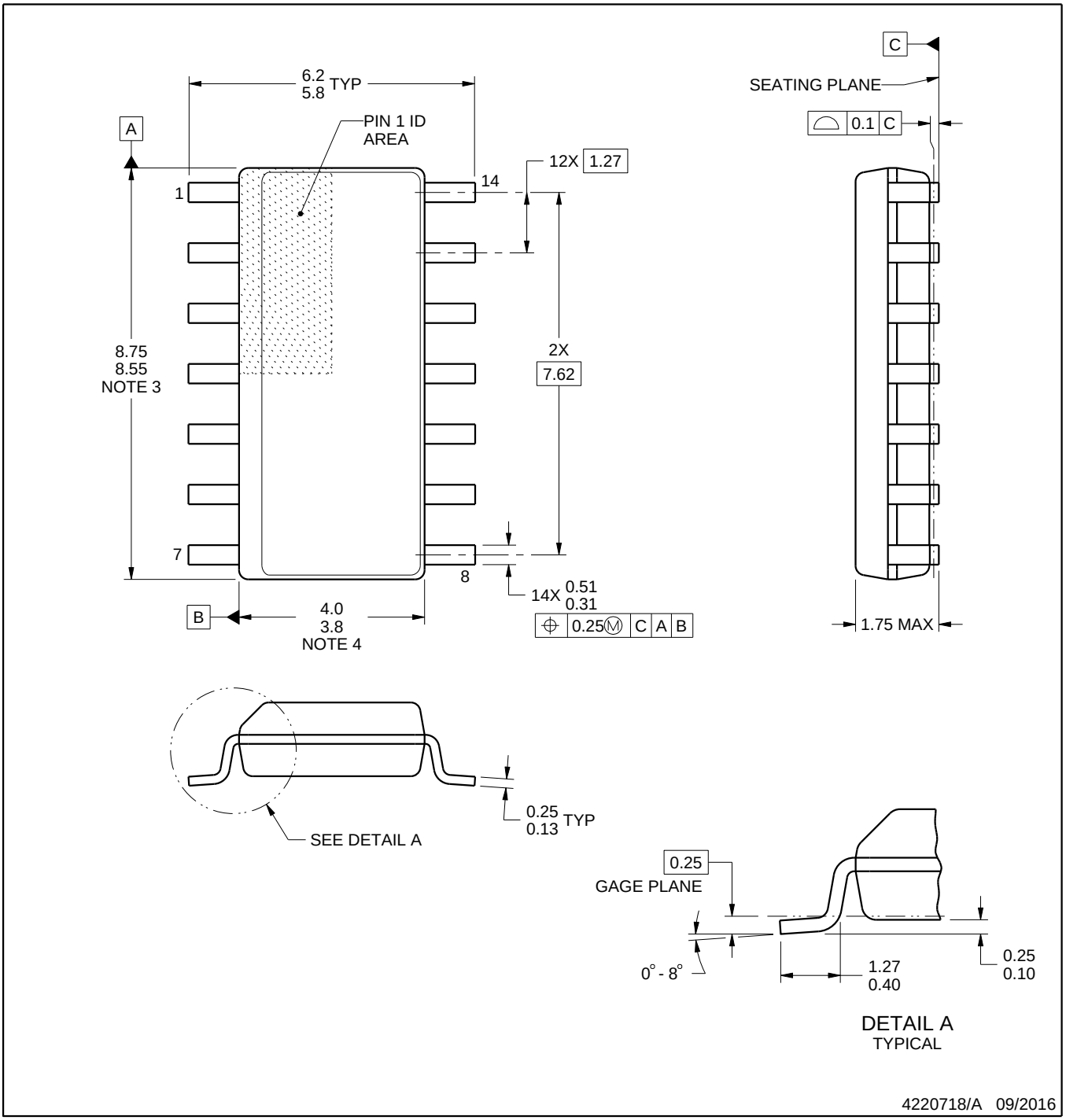


# PACKAGE OUTLINE

## D0014A

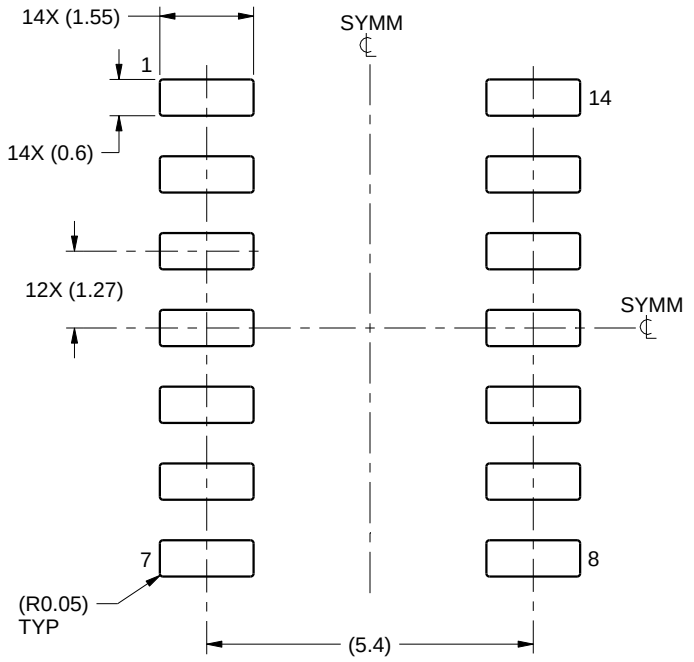
## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

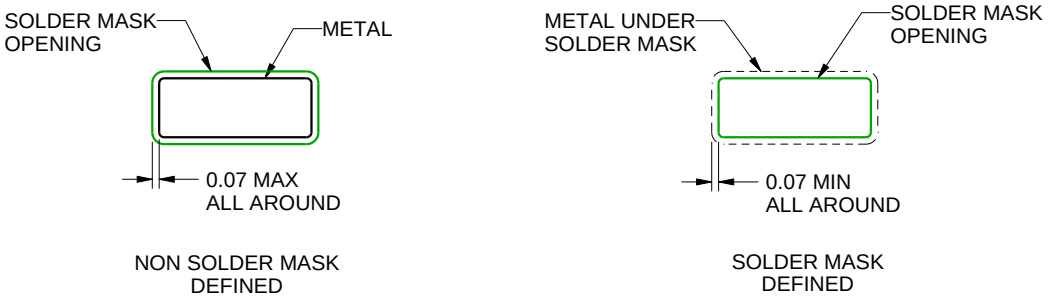



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.




LAND PATTERN EXAMPLE
SCALE:8X




SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

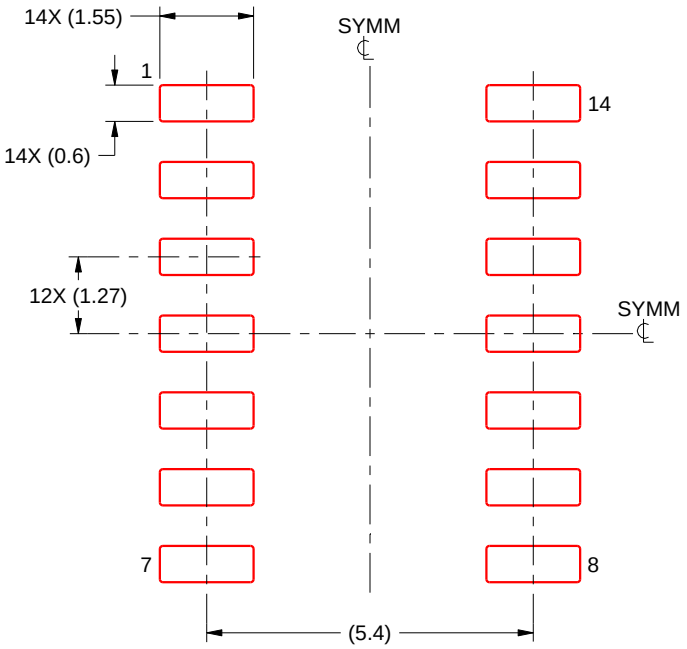
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

## D0014A

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

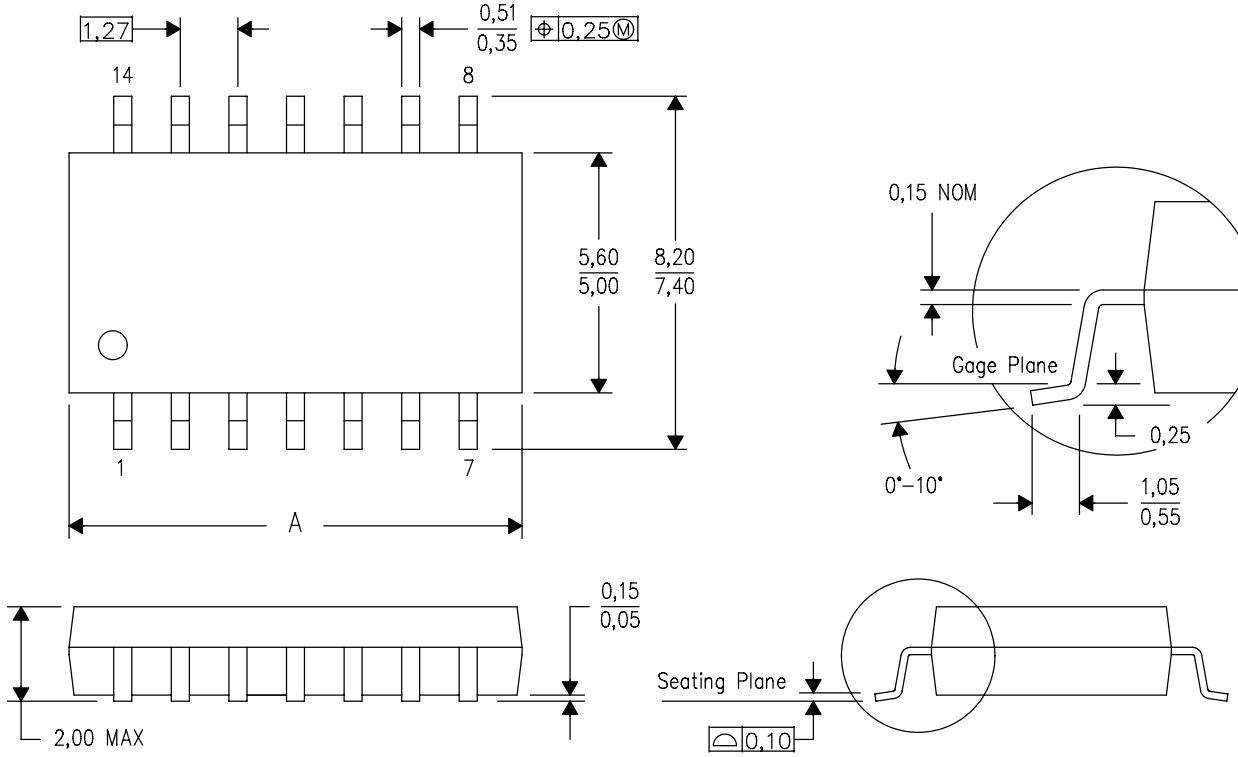
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## MECHANICAL DATA

**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

# GENERIC PACKAGE VIEW

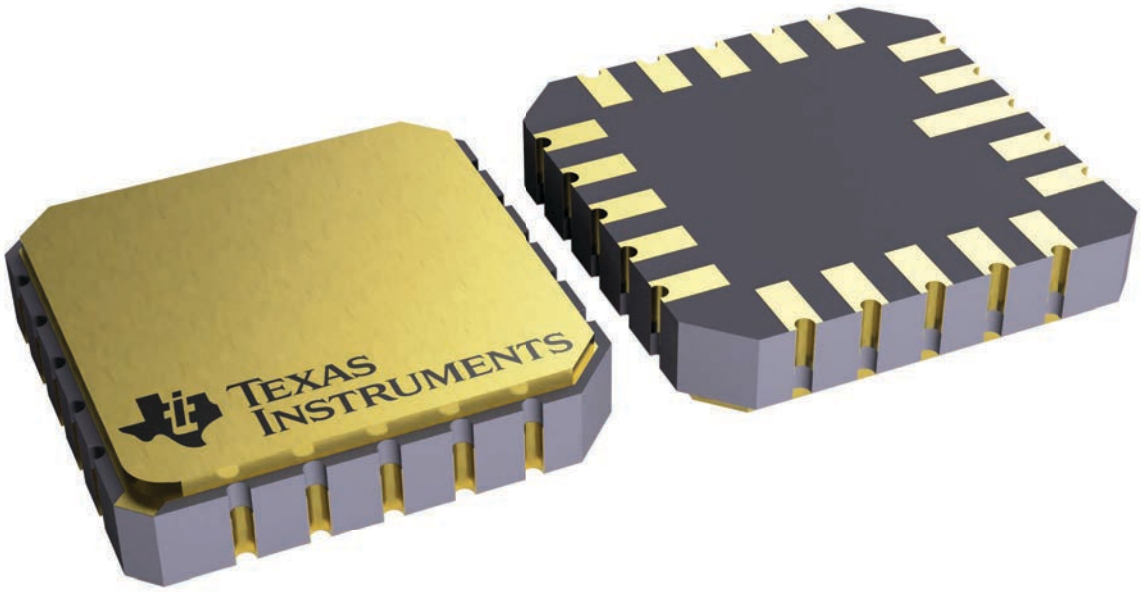
## FK 20

## LCCC - 2.03 mm max height

**8.89 x 8.89, 1.27 mm pitch**

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

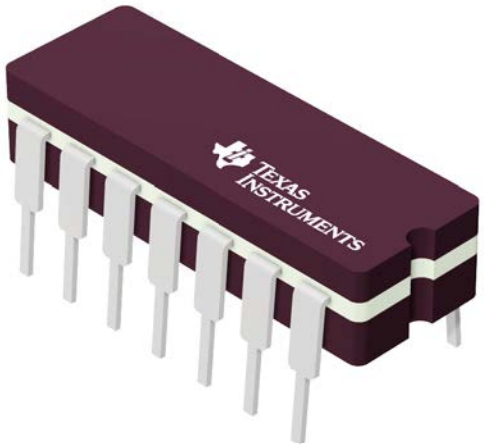



4229370VA\

# GENERIC PACKAGE VIEW

## J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE




Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

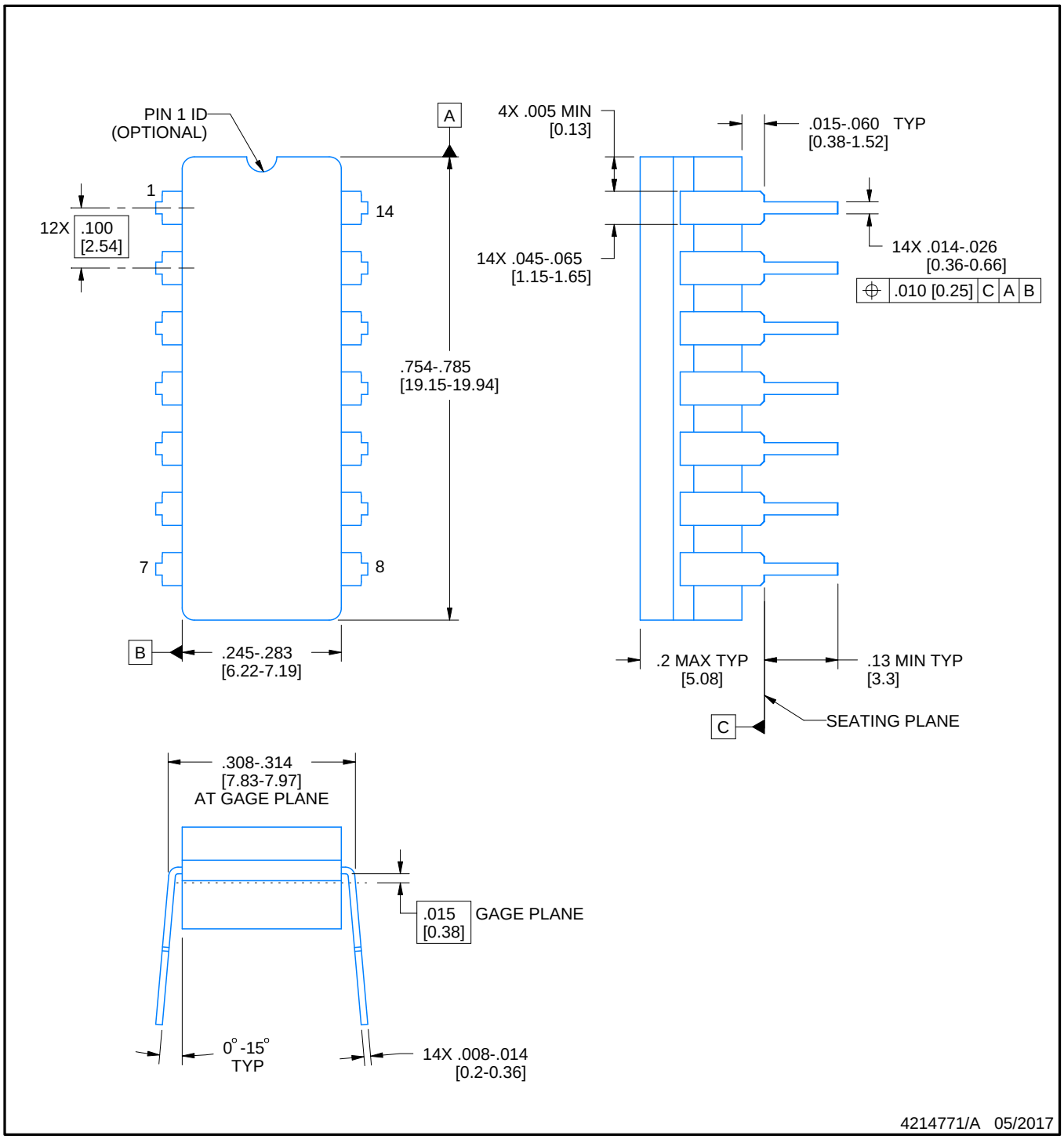
4040083-5/G

# PACKAGE OUTLINE

## J0014A

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE




NOTES:

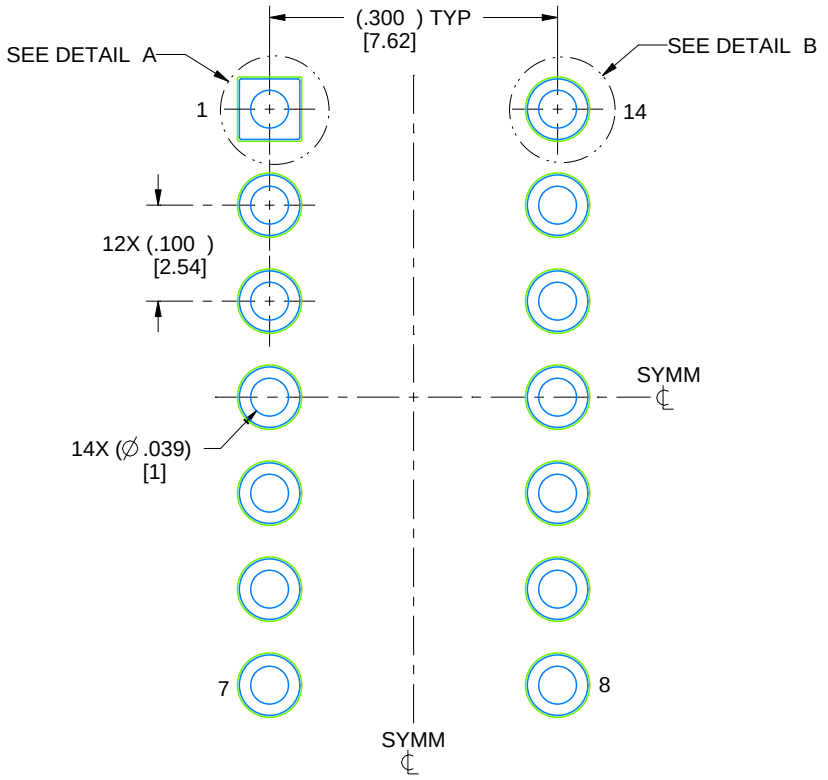
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

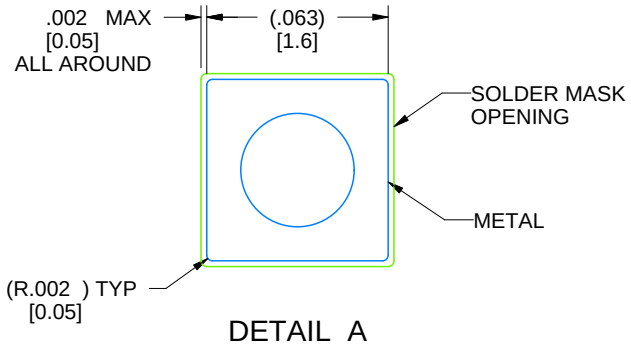
## J0014A

## CDIP - 5.08 mm max height

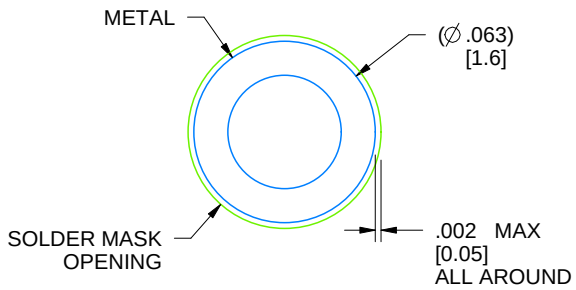
CERAMIC DUAL IN LINE PACKAGE




LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X




DETAIL A
SCALE: 15X



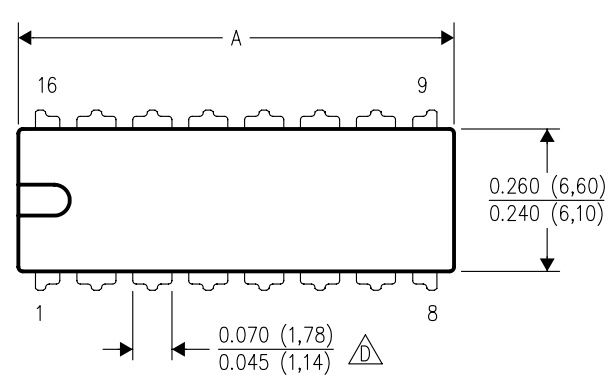

DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

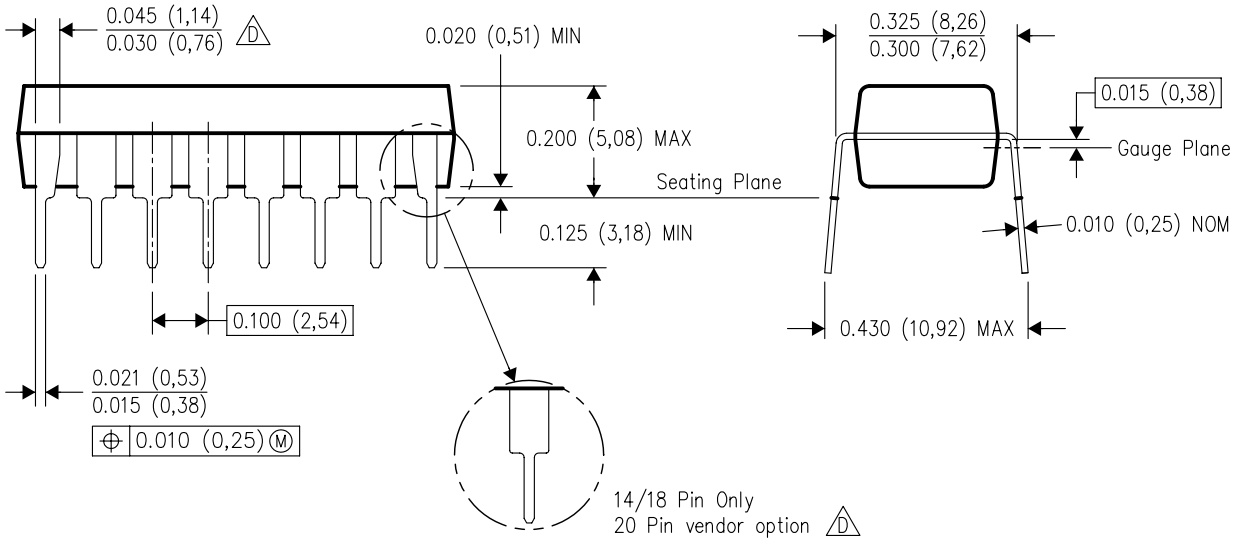
## N (R–PDIP–T**)

## PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN




| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS–001 VARIATION (C) | AA | BB | AC | AD |




4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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